



DOCKET NO. END920010002US1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Ray *et al.*

Examiner: Nguyen, Ha T

Serial No.: 09/779,812

Art Unit: 2812

Filed: 2/08/01

9/A Amold
5/3/02
D. Walk
RECEIVED
APR 25 2002
102800 MAIL ROOM

For: LEAD-FREE SOLDER STRUCTURE AND METHOD FOR HIGH FATIGUE LIFE

Commissioner for Patents
Washington D.C. 20231

Sir:

This paper is being filed in response to the Office Action mailed January 31, 2002.

Applicants respectfully request that the above-identified application be reconsidered in view of the Amendments and Remarks that follow, that each of the presently pending claims be allowed, and that the application be passed to issue.

Amendment

Please amend the above-referenced patent application as follows:

In the Claims:

Please cancel claim 11. Please add new claims 31-34. Pending claims 1-10 and 12-34 are as follows.

1. A method for forming an electronic structure, comprising the steps of:
providing a substrate; and

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